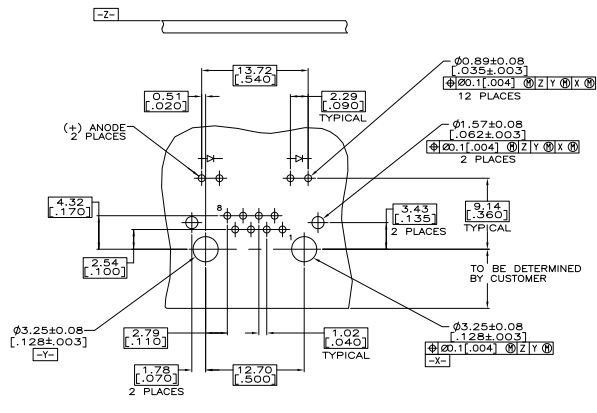
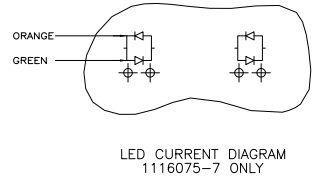


- △ MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36 THICK PHOS BRONZE PLATED WITH 3.81 μm MIN THICK MATTE TIN IN SOLDER AREA, 1.27 μm [.00050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 μm MIN THICK NICKEL.
 SHIELD - 0.196 THICK COPPER ZINC ALLOY PREPLATED WITH 1.27 μm MIN SATIN NICKEL WITH 2.03 μm MIN TIN. POST DIPPED ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51 CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 μm THICK Sn/Cu OVER 2.03 μm THICK Ag OVER 1.02 μm THICK Cu OVER 3.56 μm THICK Ni OVER 1.02 μm THICK Cu UNDERPLATE.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
 - SUGGESTED PANEL OPENING DIMENSIONS.
 - SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
 - SEE TABLE FOR COLOR OF LEADS AND NUMBER REQUIRED.
 - THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)

ORANGE/GREEN	ORANGE/GREEN	6116075-7
YELLOW	YELLOW	6116075-8
GREEN	GREEN	6116075-5
GREEN	YELLOW	6116075-4
YELLOW	-	6116075-3
-	GREEN	6116075-2
YELLOW	GREEN	6116075-1
POSITION 2	POSITION 1	PART NUMBER
INDICATOR COLOR		

THIS DRAWING IS A CONTROLLED DOCUMENT

DESIGNER	DATE	REVISED BY	DATE
114-2154	108-1163-4	100779	6116075

TE Connectivity
 INVERTED MODULAR JACK ASSEMBLY, 1X1, SHIELDED, LED